**Minutes – 020718**

**Present: IT, SW, AG, HH, PS, SB**

**Apologies: TJ, PD (at Sheffield)**

**Strip modules**

SW: Sven has done half of the drawings. In the workshop now. Bits for assembling hybrids. Worked on module frame (LS) and module jig. => do drawings this week.

We have to build 2 SS modules. Mike wirebonded this week. SW to test.

PD collecting modules from Sheffield.

Warwick have to do EDMS reviewed for their cold jig.

Get hybrids this week… to send to Stevenage. Rapped up this week. AG on holiday in August (12th-end).

**Have drawings for 1st tool. => to give to workshop. Other parts will follow on by end of this week. More jigs needed for production. Can come later.**

**Invitation to ITk week.**

QA/QC meeting next week in oxford. Mon-thurs. Cold test on Friday. QA on some hybrids. Maybe just Sw or AG for the Friday. Accommodation v. expensive.

AG: Brookhaven module works. Priority is for test frame . CMS DCDC problem fixed.

SW: building hybrids for tests, engineering drawings

**Strip Mechanics**

Drawings for 14 module stave completed. Query of envelope for module clearances. Where is distance measured from.

Dave Lyn wanted modules for 13 module stave.

Design stave tooling

DS/TJ (with Hamish) 13 module stave core.

**Pixel modules**

PD: Continue on the COB

Set up the Agilent DAQ for Ilya’s hybrid testing

Long cables continue

Would be nice to have a new hybrid module

Continue planning for RD53 modules/chips (NDA signed, YARR)

New cooling box for ring reception tests.

Pick up the long strip module from Sheffield. (Discuss the cooling box with them).

IT: start to evaluate new MINT stamp method. Good results in uniformity of glue thickness 3micron-5 micron deposit. Can reuse stamp upto 10 times. Send sample to Kirk to thermal cycle. Present at Jessica’s meeting.

IT: after qualification table, push wirebonding and pull test today. Thermal cycling will need time.

Focus on new hybrid design.

JT: make silicon mold for JT. (3D printer mold).2 RD53 chips unirradiated sent to test beam

YG: tomorrow working on testbeam. Can prepare program for YARR. AndreasK wants us to wait a week for UCL solution.

**Pixel Mechanics**

SB: working on specs doc.

*Not much progress in the last week. TJ: re-evaluted cost of half sheets – discuss with CB, JP and TJ, HH this week.*

*HH to look at Pixel EC services.*

*Work shop effort: ask for update from Mark Whitley on workshop and Peter Cooke on ATLAS effort. => standing items on LAU.*

*University cars.*

AOB: Jessica’s module arrested by American customs.